



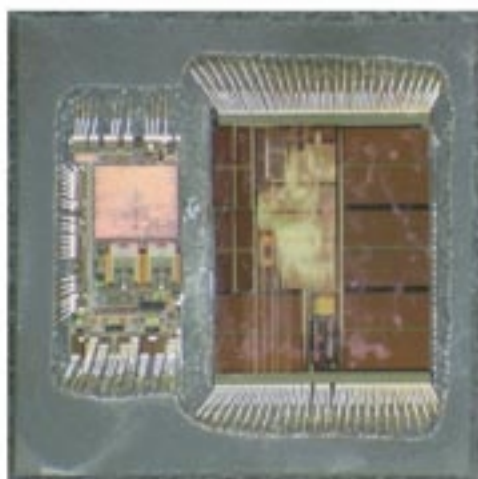
JetEtch

Automated IC Decapsulation

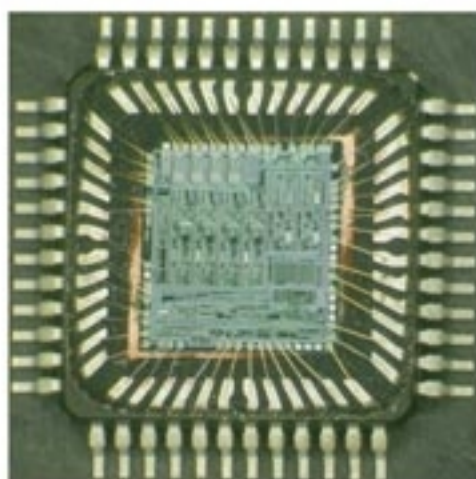
*Patented
Acid Delivery System is the
Industry Standard in
Plastic IC Decapsulation*



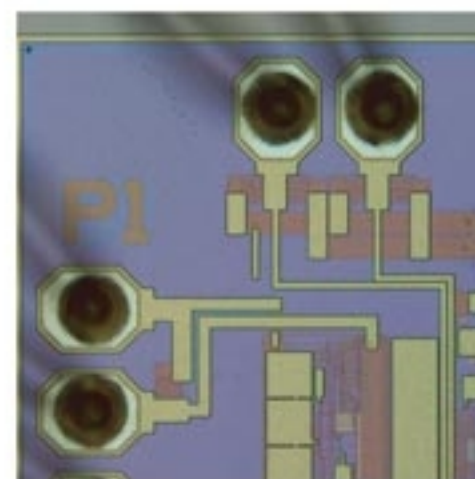
- ▲ *13 Mixed Acid Ratios - from 1:0 to 6:1 for Nitric and Sulfuric*
- ▲ *Selectable Etch Time, Temperature, and Acid Volume (mL/min)*
- ▲ *Fixed Etch Head Reduces Costs and Etch Times*
- ▲ *Dual Waste Bottle Design for Unequaled User Safety*
- ▲ *Unsurpassed Decapsulation Quality, Control, and Consistency for Virtually All Plastic ICs*



Multi-chip (MCM) sample showing complete die exposure



TSOP sample showing complete second bond exposure



Wire bond pads showing no Aluminum damage

OmniEtch

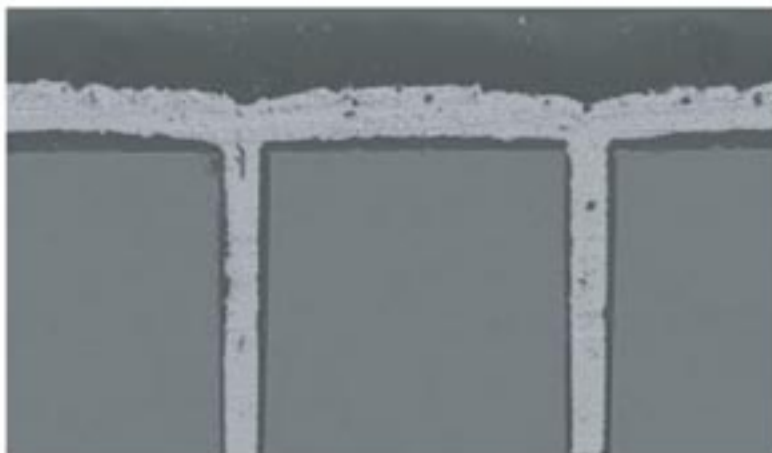
Planar Chemical Delayering



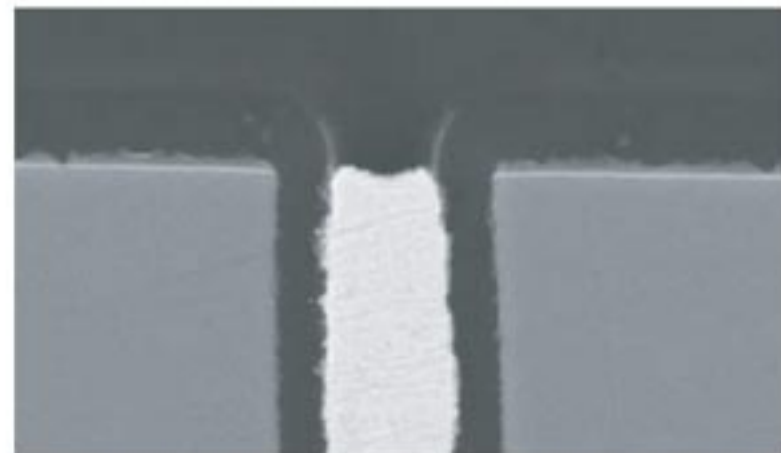
*Proprietary
Carrier Medium Gel
prevents undercutting
through
interconnect vias*

- ▲ *Controlled Chemical Etching of Copper, Aluminum, Titanium, Oxide, and Nitride Layers*
- ▲ *Selectable Etch Time and Temperature*
- ▲ *No Thermal or Mechanical Sample Damage*
- ▲ *Perfect complement to RIE and CMP*

Copper IC Cross-section



2.5-μm Via Before



2.5-μm Via After